

Replaces DS5444-4.2

DIM800DCM17-A000

IGBT Chopper Module

DS5444-5 April 2011 (LN26752)

FEATURES

- 10µs Short Circuit Withstand
- High Thermal Cycling Capability
- Non Punch Through Silicon
- Isolated AISiC Base With AIN Substrates
- Lead Free Construction

APPLICATIONS

- High Reliability Inverters
- Motor Controllers
- Traction Drives

The Powerline range of high power modules includes half bridge, chopper, dual, single and bi-directional switch configurations covering voltages from 1200V to 3300V and currents up to 2400A.

The DIM800DCM17-A000 is a 1700V, n-channel enhancement mode, insulated gate bipolar transistor (IGBT) chopper module. The IGBT has a wide reverse bias safe operating area (RBSOA) plus 10µs short circuit withstand. This device is optimised for traction drives and other applications requiring high thermal cycling capability.

The module incorporates an electrically isolated base plate and low inductance construction enabling circuit designers to optimise circuit layouts and utilise grounded heat sinks for safety.

ORDERING INFORMATION

Order As:

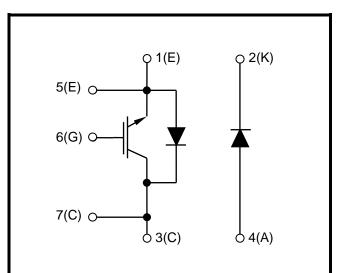
DIM800DCM17-A000

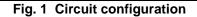
Note: When ordering, please use the complete part number

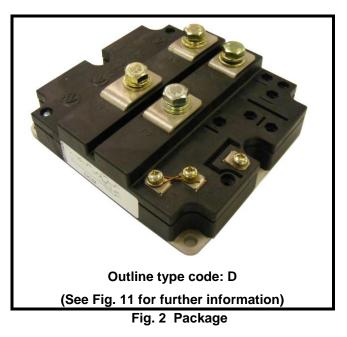
KEY PARAMETERS

V _{CES}		1700V
V _{CE(sat)}	* (typ)	2.7V
l _c `́	(max)	800A
I _{C(PK)}	(max)	1600A

* Measured at the power busbars, not the auxiliary terminals







ABSOLUTE MAXIMUM RATINGS

Stresses above those listed under 'Absolute Maximum Ratings' may cause permanent damage to the device. In extreme conditions, as with all semiconductors, this may include potentially hazardous rupture of the package. Appropriate safety precautions should always be followed. Exposure to Absolute Maximum Ratings may affect device reliability.

T_{case} = 25°C unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
V _{CES}	Collector-emitter voltage	$V_{GE} = 0V$	1700	V
V_{GES}	Gate-emitter voltage		±20	V
Ι _C	Continuous collector current	$T_{case} = 75^{\circ}C$	800	А
I _{C(PK)}	Peak collector current	1ms, T _{case} = 110°C	1600	А
P _{max}	Max. transistor power dissipation	$T_{case} = 25^{\circ}C, T_{j} = 150^{\circ}C$	6940	W
l ² t	Diode I ² t value (IGBT arm)	V 0 t 10mg T 125%	120	kA ² s
	Diode I ² t value (Diode arm)	$V_R = 0, t_p = 10 \text{ms}, T_j = 125^{\circ}\text{C}$	270	kA ² s
V _{isol}	Isolation voltage – per module	Commoned terminals to base plate. AC RMS, 1 min, 50Hz	4000	V
Q _{PD}	Partial discharge – per module	IEC1287, V ₁ = 1800V, V ₂ = 1300V, 50Hz RMS	10	рС

THERMAL AND MECHANICAL RATINGS

Internal insulation material:	AIN
Baseplate material:	AISiC
Creepage distance:	20mm
Clearance:	10mm
CTI (Comparative Tracking Index):	350

Symbol	Parameter	Test Conditions	Min	Тур.	Мах	Units
R _{th(j-c)}	Thermal resistance – transistor (per arm)	Continuous dissipation – junction to case	-	-	18	°C/kW
Р	Thermal resistance – diode (IGBT arm)	Continuous dissipation –	-	-	40	°C/kW
B ₄ (t)		junction to case			26.7	°C/kW
R _{th(c-h)}	Thermal resistance – case to heatsink (per module)	Mounting torque 5Nm (with mounting grease)	-	-	8	°C/kW
Tj	Junction temperature	Transistor	-	-	150	°C
		Diode	-	-	125	°C
T _{stg}	Storage temperature range	-	-40	-	125	°C
		Mounting – M6	-	-	5	Nm
	Screw torque	Electrical connections – M4	-	-	2	Nm
		Electrical connections – M8	-	-	10	Nm

ELECTRICAL CHARACTERISTICS

T_{case} = 25°C unless stated otherwise.

Symbol	Parameter	Test Conditions	Min	Тур	Мах	Units
	Collector cut-off current	$V_{GE} = 0V, V_{CE} = V_{CES}$			1	mA
I _{CES}		$V_{GE} = 0V, V_{CE} = V_{CES}, T_{case} = 125^{\circ}C$			25	mA
I _{GES}	Gate leakage current	$V_{GE} = \pm 20V, V_{CE} = 0V$			4	μA
$V_{\text{GE(TH)}}$	Gate threshold voltage	I_{C} = 40mA, V_{GE} = V_{CE}	4.5	5.5	6.5	V
v t	Collector-emitter saturation	$V_{GE} = 15V, I_{C} = 800A$		2.7	3.2	V
$V_{CE(sat)}^{\dagger}$	voltage	$V_{GE} = 15V, I_C = 800A, T_j = 125^{\circ}C$		3.4	4.0	V
I _F	Diode forward current	DC		800		А
I _{FM}	Diode maximum forward current	t _p = 1ms		1600		А
	Diode forward voltage (IGBT arm) Diode forward voltage (Diode arm)	- I _F = 800A		2.2	2.5	V
				2.0	2.3	V
V_{F}^{\dagger}	Diode forward voltage (IGBT arm)	L = 8000 T = 125°C		2.3	2.6	V
	Diode forward voltage (Diode arm)	$I_F = 800A, T_j = 125^{\circ}C$		2.0	2.3	V
C _{ies}	Input capacitance	V_{CE} = 25V, V_{GE} = 0V, f = 1MHz		60		nF
Q_g	Gate charge	±15V		9		μC
C _{res}	Reverse transfer capacitance	$V_{CE} = 25V, V_{GE} = 0V, f = 1MHz$				nF
L _M	Module inductance – per arm			20		nH
R _{INT}	Internal transistor resistance – per arm			270		μΩ
SC _{Data}	Short circuit current, I _{SC}	$\begin{split} T_{j} &= 125^{\circ}C, \ V_{CC} = 1000V \\ t_{p} &\leq 10 \mu s, \ V_{GE} \leq 15V \\ V_{CE \ (max)} &= V_{CES} - L^{*} \ x \ dl/dt \\ IEC \ 60747-9 \end{split}$		3200		A

Note:

[†] Measured at the power busbars, not the auxiliary terminals ^{*} L is the circuit inductance + L_M

ELECTRICAL CHARACTERISTICS

T_{case} = 25°C unless stated otherwise

Symbol	Parameter	Test Conditions	Min	Тур.	Max	Units
t _{d(off)}	Turn-off delay time			1250		ns
t _f	Fall time	$I_{\rm C} = 800 \text{A}$ $V_{\rm GE} = \pm 15 \text{V}$		170		ns
E _{OFF}	Turn-off energy loss	$V_{GE} = \pm 15V$ $V_{CE} = 900V$		230		mJ
t _{d(on)}	Turn-on delay time	$R_{G(ON)} = 2.2\Omega$		250		ns
t _r	Rise time	$R_{G(OFF)} = 2.2\Omega$ $L_{S} \sim 100 \text{nH}$		250		ns
E _{ON}	Turn-on energy loss			275		mJ
Q _{rr}	Diode reverse recovery charge	IGBT arm		200		μC
I _{rr}	Diode reverse recovery current	I _F = 800A V _{CE} = 900V		460		А
E _{rec}	Diode reverse recovery energy	dl _F /dt = 4000A/µs		130		mJ
Q _{rr}	Diode reverse recovery charge	Diode arm		250		μC
I _{rr}	Diode reverse recovery current	I _F = 800A V _{CE} = 900V		530		А
E _{rec}	Diode reverse recovery energy	dl _F /dt = 4000A/µs		160		mJ

T_{case} = 125°C unless stated otherwise

Symbol	Parameter	Test Conditions	Min	Тур.	Max	Units
t _{d(off)}	Turn-off delay time			1500		ns
t _f	Fall time	$I_{C} = 800A$ $V_{GE} = \pm 15V$		200		ns
E _{OFF}	Turn-off energy loss	$V_{GE} = \pm 15V$ $V_{CE} = 900V$		360		mJ
t _{d(on)}	Turn-on delay time	$R_{G(ON)} = 2.2\Omega$		400		ns
t _r	Rise time	$R_{G(OFF)} = 2.2\Omega$ $L_{S} \sim 100 \text{nH}$		250		ns
E _{ON}	Turn-on energy loss			425		mJ
Q _{rr}	Diode reverse recovery charge	IGBT arm		330		μC
Irr	Diode reverse recovery current	I _F = 800A V _{CE} = 900V		530		А
E _{rec}	Diode reverse recovery energy	dl _F /dt = 4000A/µs		200		mJ
Q _{rr}	Diode reverse recovery charge	Diode arm		425		μC
I _{rr}	Diode reverse recovery current	I _F = 800A V _{CE} = 900V		600		А
E _{rec}	Diode reverse recovery energy	dl _F /dt = 4000A/µs		250		mJ

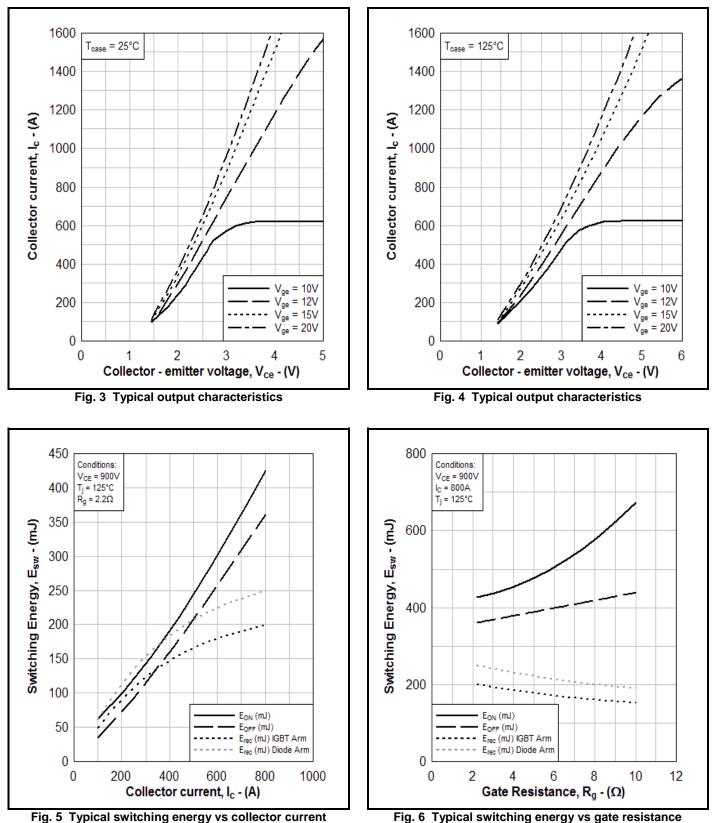


Fig. 6 Typical switching energy vs gate resistance

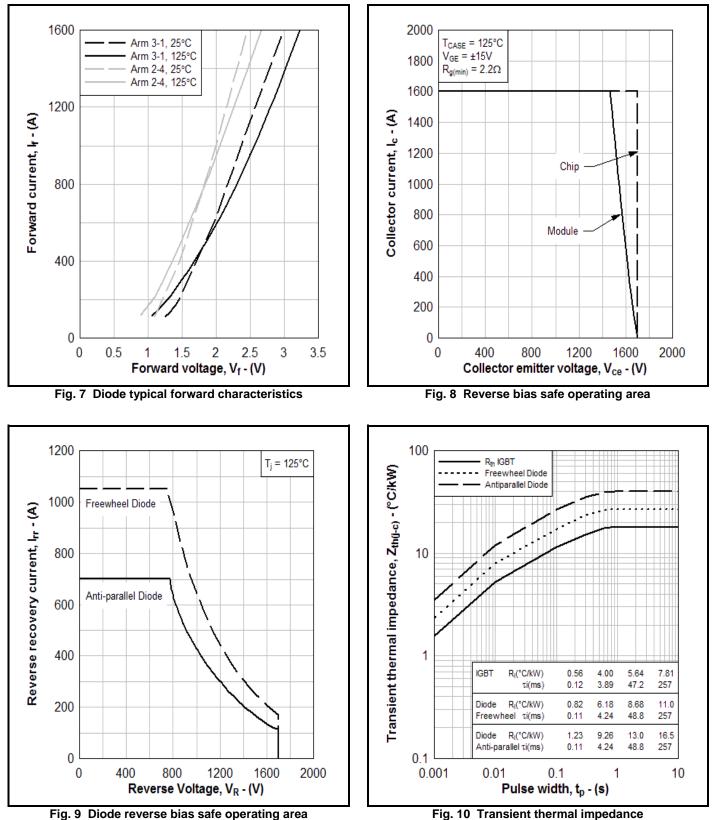
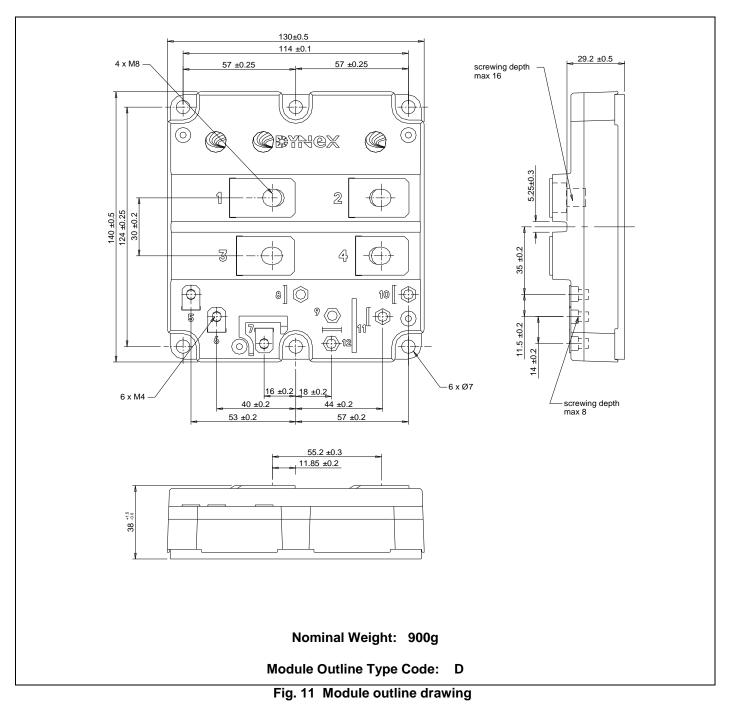


Fig. 10 Transient thermal impedance

PACKAGE DETAILS

For further package information, please visit our website or contact Customer Services. All dimensions in mm, unless stated otherwise. **DO NOT SCALE.**



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